

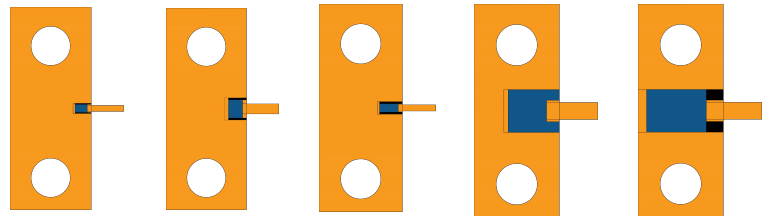


DC - 30.0 GHz.

Model: CVDT-XXXX-F-50

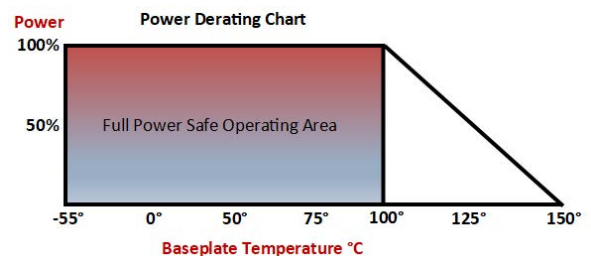
Chip Configurations

0402, 0505, 0603, 1310, 2010

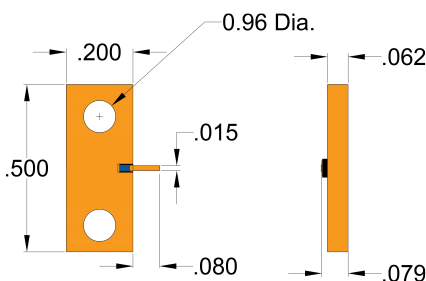


DIA-FILM Chip terminations are manufactured using CVD Diamond substrate material which has the highest thermal conductivity of any material known to man for use with electronic components. These termination chips are offered in various standard sizes having the capability of dissipating 20 - 200 watts of CW power and operate from -65°C to +150°C. With a low dielectric constant CVD Diamond is an excellent choice for high frequency design. The resistor structure is all thin-film utilizing the latest thin-film processing and pure metals. The resistor material is self-passivating Tantalum/Nitride combined with Titanium/Tungsten, Palladium, nickel and Gold films which produces these high reliability components. These terminations are supplied with Copper, Gold Plated tabs and are attached with Gold/Tin brazing material at 280°C. Soft-Solder attachment is recommended using SN-96 Eutectic Solder. Silver epoxy can be used but not recommended for power dissipation over 1 watt. They can be delivered in Gel-Pak, Waffle packaging or Anti-Static hinged boxes with foam. Please contact the factory for any special requirements or packaging. Anti-Static boxes standard packaging. All chips are RoHS compliant and are designed to meet MIL-PRF-55342.

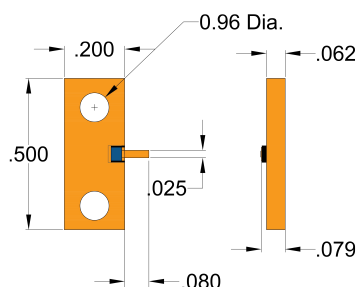
CVD DIAMOND FLANGE TERMINATION SELECTION CHART				
Part Number	Resistance (Ω) ±5%	Frequency Range	Power (Watts)	VSWR (Max)
CVDT-0402-F-50	50.0	DC - 8 GHz	10	1.6:1
CVDT-0505-F-50	50.0	DC - 20 GHz	50	1.6:1
CVDT-0603-F-50	50.0	DC - 28 GHz	50	1.6:1
CVDT-1310-F-50	50.0	DC - 14 GHz	150	1.6:1
CVDT-2010-F-50	50.0	DC - 12 GHz	200	1.6:1



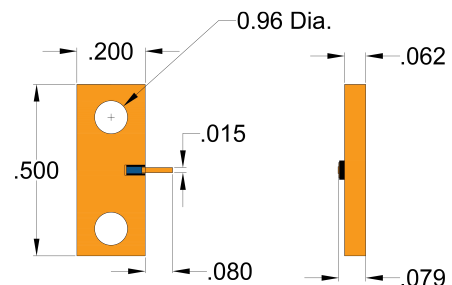
CVT-0402-F50



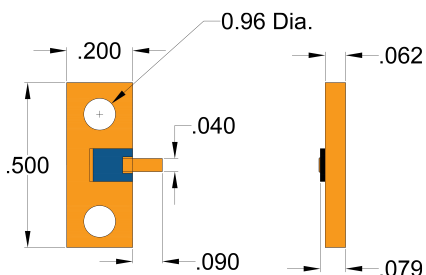
CVT-0505-F50



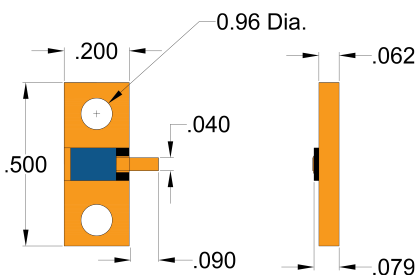
CVT-0603-F50



CVT-01310-F50



CVT-2010-F50



Part Number Example:

